

Description

The ZXGD3101 is intended to drive MOSFETS configured as ideal diode replacements. The device is comprised of a differential amplifier detector stage and high current driver. The detector monitors the reverse voltage of the MOSFET such that if body diode conduction occurs a positive voltage is applied to the MOSFET's Gate pin.

Once the positive voltage is applied to the Gate the MOSFET switches on allowing reverse current flow. The detectors' output voltage is then proportional to the MOSFET Drain-Source reverse voltage drop and this is applied to the Gate via the driver. This action provides a rapid turn off as current decays.

Application

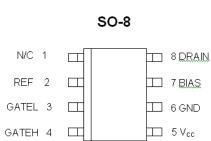
- Flyback Converters in:
 - Adaptors
 - LCD Monitors
 - Server PSU's
 - Set Top Boxes
- LLC Converter in:
 - High Power Adaptors
 - LCD TV
 - Street Lighting

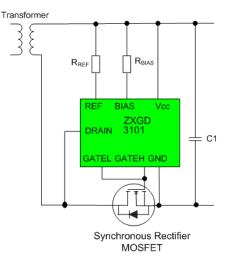
Features

- Turn-off propagation delay 15ns and turn-off time 20ns.
- Suitable for Discontinuous Mode (DCM), Critical Conduction Mode (CrCM) and Continuous Mode (CCM) operation
- Compliant with Energy Star V2.0 and European Code of Conduct V3
- Halogen Free part
- 5-15V Vcc range

Mechanical Data

- Case: SO-8
- Marking Information: See Page 13





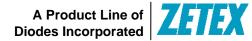
Pin out details

Typical Configuration

Ordering Information

Product	Status	Package	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXGD3101N8TC	Active	SO-8	ZXGD3101	13	12	2500







Maximum Ratings

Parameter	Symbol	Limit	Unit
Supply voltage (Note 1)	V _{CC}	15	V
Continuous Drain pin voltage (Note 1)	V _D	-3 to180	V
GATEH and GATEL output Voltage (Note 1)	V _G	-3 to V _{cc} + 3	V
Driver peak source current	ISOURCE	4	А
Driver peak sink current	I _{SINK}	7	А
Reference current	I _{REF}	25	mA
Bias voltage	V _{BIAS}	V _{cc}	V
Bias current	I _{BIAS}	100	mA
Power dissipation at $T_A = 25^{\circ}C$	PD	490	mW
Operating junction temperature	TJ	-40 to +150	°C
Storage temperature	T _{STG}	-50 to +150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit	
Junction to ambient (Note 2)	R _{0JA}	255	°C/W	
Junction to lead (Note 3)	R _{0IA}	120	°C/W	

ESD Rating

Model	Rating	Unit
Human Body	4000	V
Machine	400	V

Notes:

All voltages are relative to GND pin
 Mounted on minimum 1oz weight copper on FR4 PCB in still air conditions.

3. Output Drivers - Junction to solder point at end of the lead 5 and 6







Electrical Characteristics $@T_A = 25^{\circ}C$, $V_{CC} = 10V$, $R_{BIAS} = 1.8k\Omega$, $R_{REF} = 3k\Omega$									
Parameter Sy		Conditions	Тур.	Max.	Unit				
Input and supply characteristics									
On anothing assume to		V _{DRAIN} ≤ -200m V	-	3	-				
Operating current	I _{OP}	V _{DRAIN} ≥ 0V	-	8	-	mA			
Gate Driver									
Turn-off Threshold Voltage(Note 4)	VT	V _G = 1V, (Note 5)	-45	-16	0	mV			
	V _{G(off)}	V _{DRAIN} ≥ 0V, (Note 5)	-	0.6	1				
	V _G	V _{DRAIN} = -60mV, (Note 6)	5.0	7.5	-				
GATE output voltage (Note 4)		V _{DRAIN} = -80mV, (Note 6)	7.0	8.5	-	v			
		V _{DRAIN} = -100mV, (Note 6)	8.4	9	-				
		V _{DRAIN} ≤ -140mV, (Note 6)	9.2	9.4	-				
		V _{DRAIN} ≤ -200mV, (Note 6)	9.3	9.5	-				
GATEH peak source current	I _{SOURCE}	V _{GH} = 1V		2.5	-	А			
GATEL peak sink current	I _{SINK}	$V_{GL} = 5V$		2.5	-	А			
Turn on Propagation delay	t _{d1}			525		ns			
Turn off Propagation delay	t _{d2}	C _L = 2.2nF, (Notes 6 and 7)		15		ns			
Gate rise time	tr			305		ns			
Gate fall time	t _f			20		ns			

Notes: 4. GATEH connected to GATEL

5. $R_H = 100 k\Omega$, $R_L = O/C$

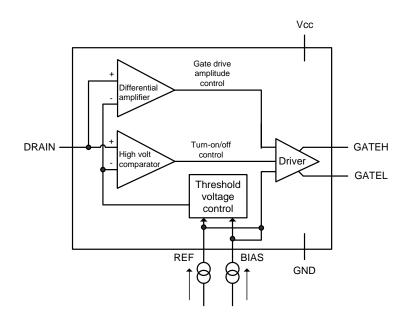
6. $R_L = 100k\Omega$, $R_H = O/C$ 7. Refer to Fig 6: test circuit and Fig 7: timing diagram on Page 12







Schematic Symbol and Pin Out Details

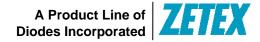


Pin No.	Symbol	Description and function
1	NC	No connection This pin can be connected to GND
2	REF	Reference This pin is connected to V _{CC} via resistor, R _{REF} . R _{REF} should be selected to source approximately 3mA into this pin. (Note 8)
3	GATEL	Gate turn off This pin sinks current, I _{SINK} , from the synchronous MOSFET Gate.
4	GATEH	Gate turn on This pin sources current, I _{SOURCE} , to the synchronous MOSFET Gate.
5	V _{cc}	Power Supply This is the supply pin. It is recommended to decouple this point to ground closely with a ceramic capacitor.
6	GND	Ground This is the ground reference point. Connect to the synchronous MOSFET Source terminal.
7	BIAS	Bias This pin is connected to V_{CC} via resistor, R _{BIAS} . R _{BIAS} should be selected to source 1.6 times I _{REF} into this pin. (Note 9)
8	DRAIN	Drain connection This pin connects directly to the synchronous MOSFET Drain terminal.

 Notes:
 8. REF pin should be assumed to be at GND +0.7V.
 9. BIAS pin should be assumed to be at GND +0.3V.

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Operation

Normal Operation

The operation of the device is described step-by-step with reference to the timing diagram below.

1. The detector monitors the MOSFET Drain-Source voltage.

2. When, due to transformer action, the MOSFET body diode is forced to conduct there is approximately -0.6V on the Drain pin.

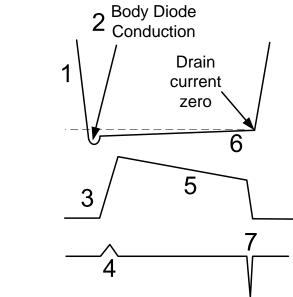
3. The detector outputs a positive voltage with respect to ground, this voltage is then fed to the MOSFET driver stage and current is sourced out of the GATEH pin.

4. The current out of the GATEH pin is sourced into the synchronous MOSFET Gate to turn the device on.

5. The GATEH output voltage is now proportional to the Drain-Source voltage drop across the MOSFET due to the current flowing through the MOSFET.

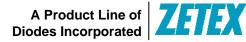
6. MOSFET conduction continues until the drain current reaches zero.

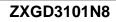
7. At zero current the detector output voltage is zero and the synchronous MOSFET Gate voltage is pulled low by the GATEL, turning the device off.

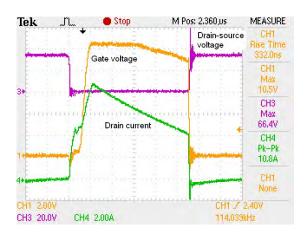


MOSFET Gate Current

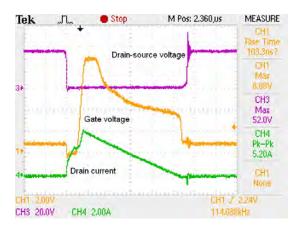




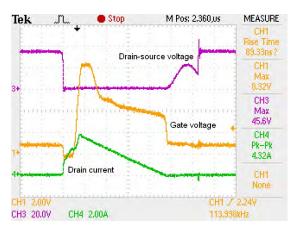




1a) Continuous Conduction Mode (CCM)







1c) Discontinuous Conduction Mode (DCM)

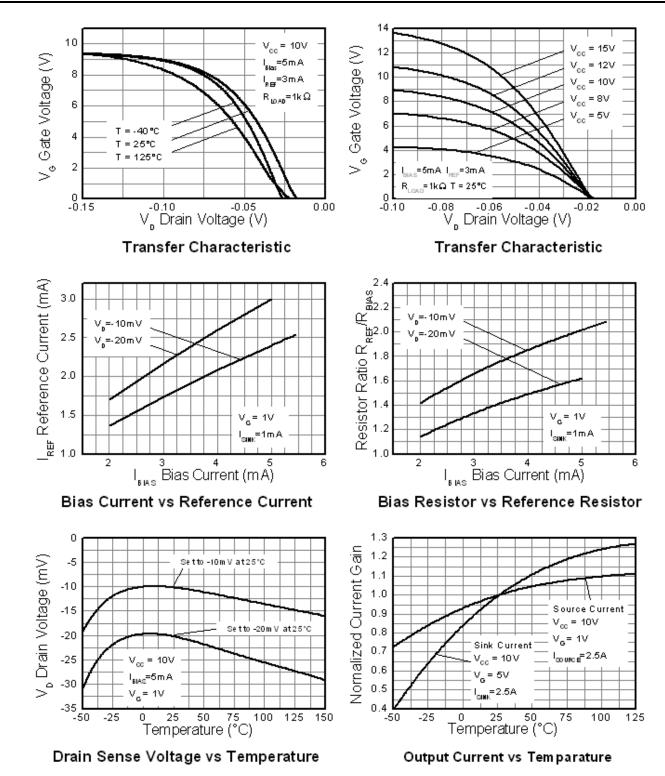




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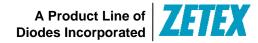


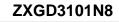
SYNCHRONOUS RECTIFIER CONTROLLER



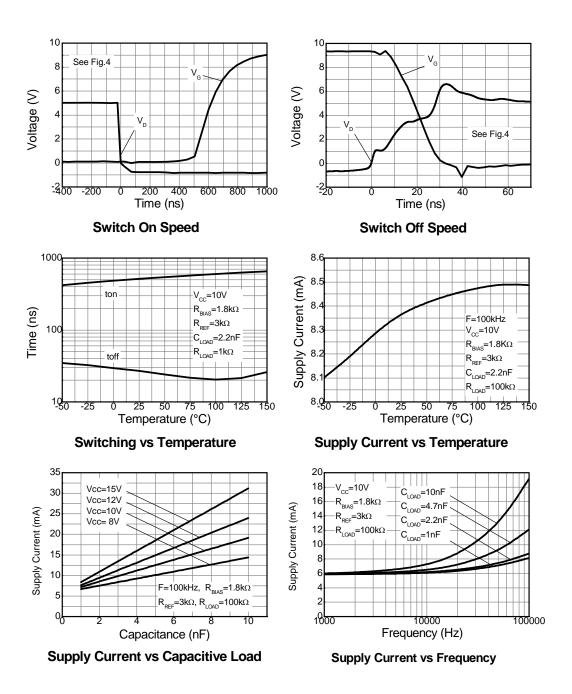
Typical Characteristics







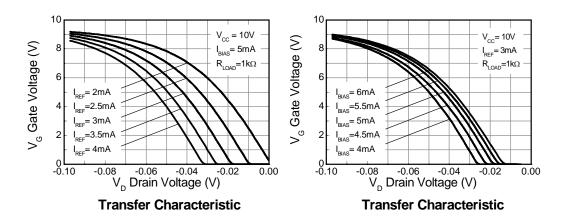
Typical Characteristics











Component Selection

It is advisable to decouple the ZXGD3101 closely to V_{CC} and ground due to the possibility of high peak gate currents with C1 in Figure 2.

The proper selection of external resistors R_{REF} and R_{BIAS} is important to the optimum device operation. Select a value for resistor R_{REF} to give a reference current, I_{REF} , of ~3mA. The value of R_{BIAS} must then be 0.6 times the value of R_{REF} giving a bias current, I_{BIAS} , of ~1.6 times I_{REF} . This provides a recommended typical offset voltage of ~20mV.

External gate resistors are optional. They can be inserted to control the rise times which may help with EMI issues, power supply consumption issues or dissipation within the part.

 $R_{REF} = (V_{CC} - 0.7V) / 0.003$

 $R_{BIAS} = (V_{CC} - 0.3V) / 0.005$

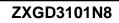
Layout considerations

The Gate pins should be as close to the MOSFET Gate as possible. Also the ground return loop should be as short as possible. The decoupling capacitor should be close to the V_{cc} and Ground pin, and should be a X7R type.

For more detailed information refer to application note AN54..







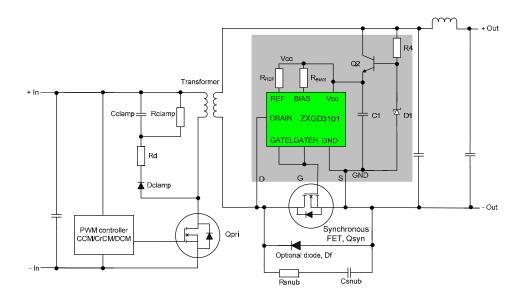


Figure 2 Example connection for low side synchronous rectification

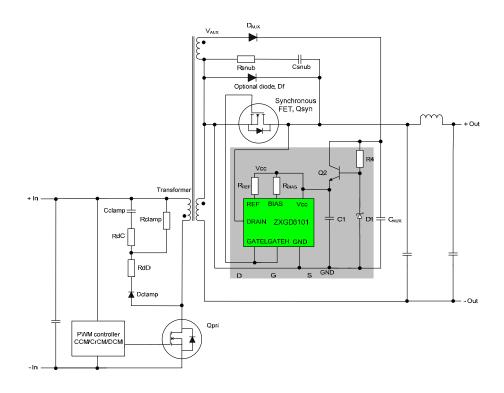
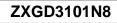


Figure 3: Example connection for high side synchronous rectification







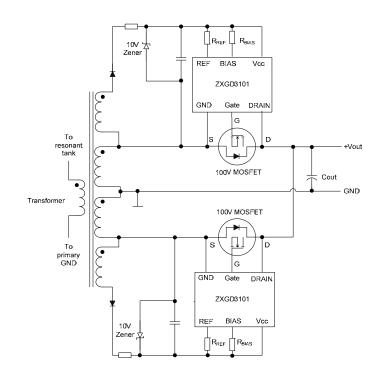
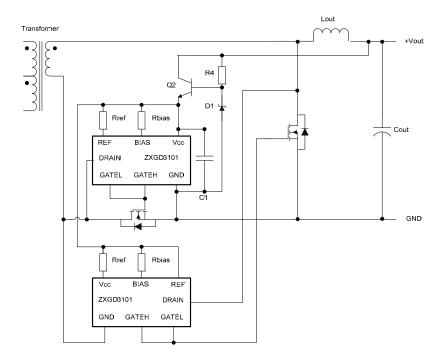
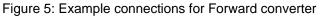
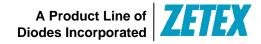


Figure 4: Example connections for LLC converter

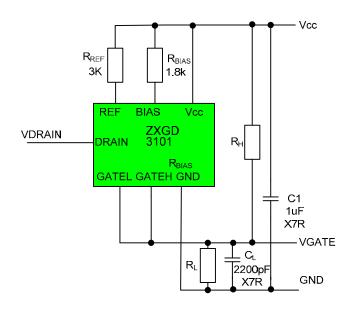


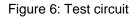












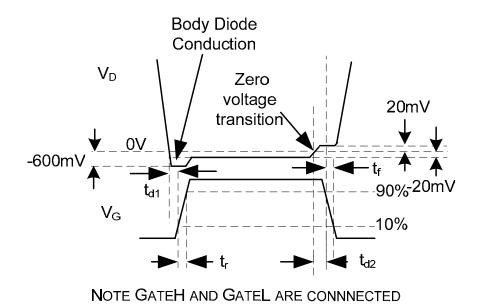
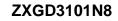


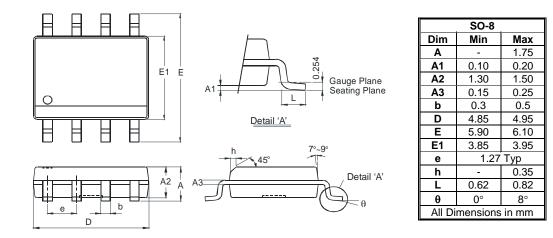
Figure 7: Timing Diagram



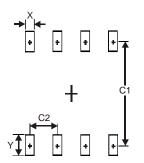




Package Outline and Dimensions

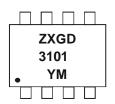


Suggested Pad Layout



Dimensions	Value (in mm)				
Х	0.60				
Y	1.55				
C1	5.4				
C2	1.27				

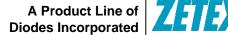
Marking Information

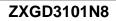


 $\begin{aligned} & ZXGD3101 = Product Type Marking Code \\ & YM = Date Code Marking \\ & Y = Year (ex. W = 2009) \\ & M = Month (ex. 9 = September) \end{aligned}$

Date Code Key												
Year	200	9	2010		2011	20)12	2013		2014	2	2015
Code	W		Х		Y		Z	А		В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D







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